

L293, L293D QUADRUPLE HALF-H DRIVERS

SLRS008C – SEPTEMBER 1986 – REVISED NOVEMBER 2004

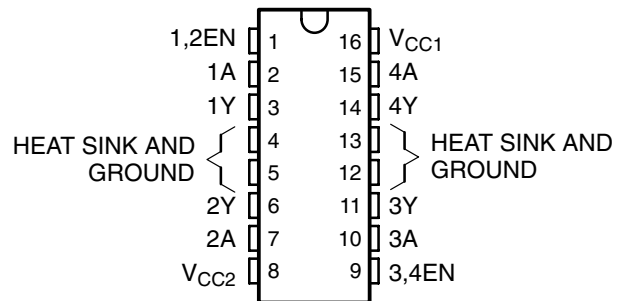
- Featuring Unitrode L293 and L293D Products Now From Texas Instruments
- Wide Supply-Voltage Range: 4.5 V to 36 V
- Separate Input-Logic Supply
- Internal ESD Protection
- Thermal Shutdown
- High-Noise-Immunity Inputs
- Functionally Similar to SGS L293 and SGS L293D
- Output Current 1 A Per Channel (600 mA for L293D)
- Peak Output Current 2 A Per Channel (1.2 A for L293D)
- Output Clamp Diodes for Inductive Transient Suppression (L293D)

description/ordering information

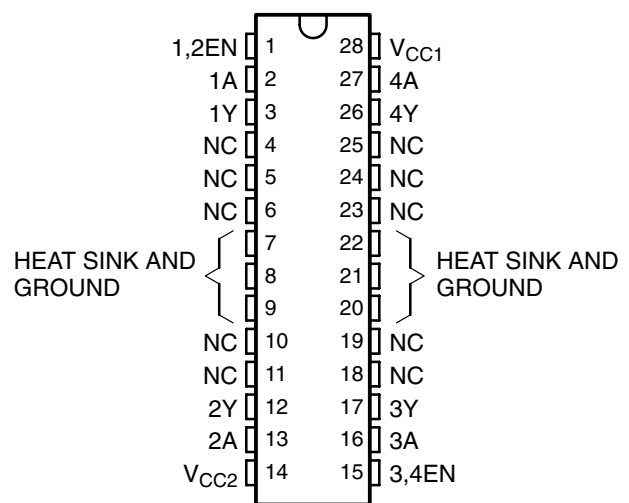
The L293 and L293D are quadruple high-current half-H drivers. The L293 is designed to provide bidirectional drive currents of up to 1 A at voltages from 4.5 V to 36 V. The L293D is designed to provide bidirectional drive currents of up to 600-mA at voltages from 4.5 V to 36 V. Both devices are designed to drive inductive loads such as relays, solenoids, dc and bipolar stepping motors, as well as other high-current/high-voltage loads in positive-supply applications.

All inputs are TTL compatible. Each output is a complete totem-pole drive circuit, with a Darlington transistor sink and a pseudo-Darlington source. Drivers are enabled in pairs, with drivers 1 and 2 enabled by 1,2EN and drivers 3 and 4 enabled by 3,4EN. When an enable input is high, the associated drivers are enabled, and their outputs are active and in phase with their inputs. When the enable input is low, those drivers are disabled, and their outputs are off and in the high-impedance state. With the proper data inputs, each pair of drivers forms a full-H (or bridge) reversible drive suitable for solenoid or motor applications.

L293 . . . N OR NE PACKAGE
L293D . . . NE PACKAGE
(TOP VIEW)



L293 . . . DWP PACKAGE
(TOP VIEW)



ORDERING INFORMATION

T _A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	HSOP (DWP)	Tube of 20	L293DWP	L293DWP
	PDIP (N)	Tube of 25	L293N	L293N
	PDIP (NE)	Tube of 25	L293NE	L293NE
		Tube of 25	L293DNE	L293DNE

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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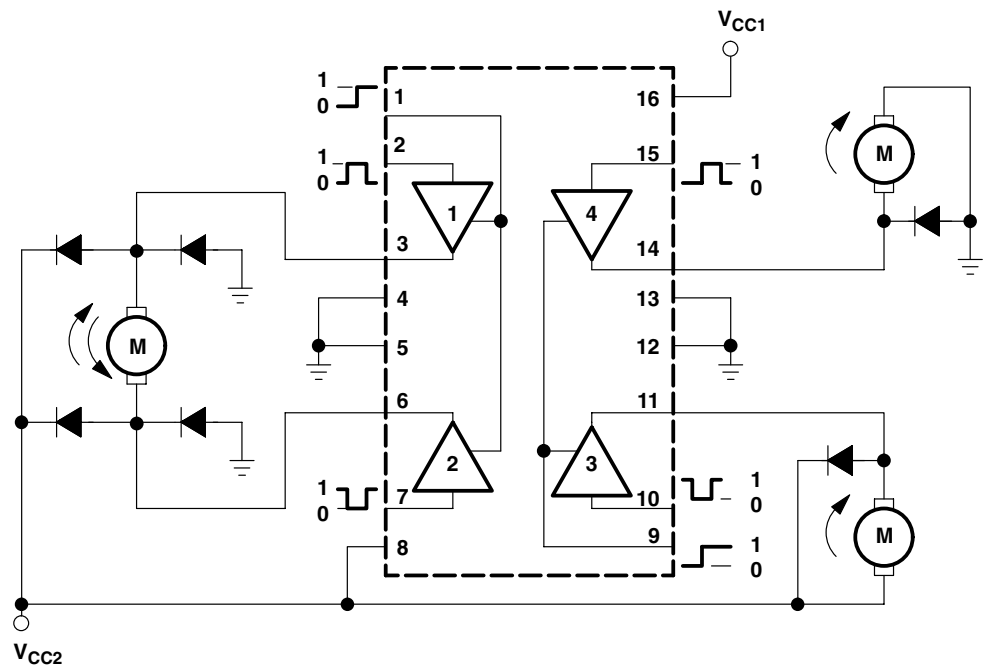
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description/ordering information (continued)

On the L293, external high-speed output clamp diodes should be used for inductive transient suppression. A V_{CC1} terminal, separate from V_{CC2} , is provided for the logic inputs to minimize device power dissipation. The L293 and L293D are characterized for operation from 0°C to 70°C.

block diagram



NOTE: Output diodes are internal in L293D.

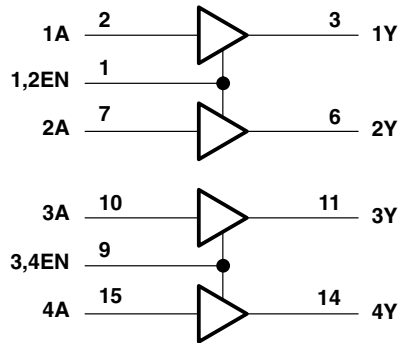
FUNCTION TABLE
(each driver)

INPUTS†		OUTPUT Y
A	EN	
H	H	H
L	H	L
X	L	Z

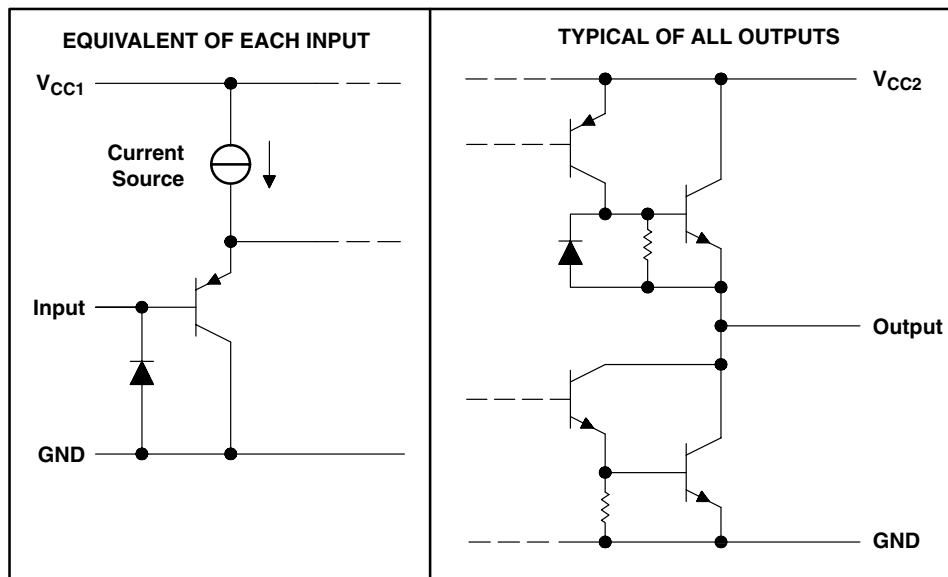
H = high level, L = low level, X = irrelevant,
Z = high impedance (off)

† In the thermal shutdown mode, the output is
in the high-impedance state, regardless of
the input levels.

logic diagram



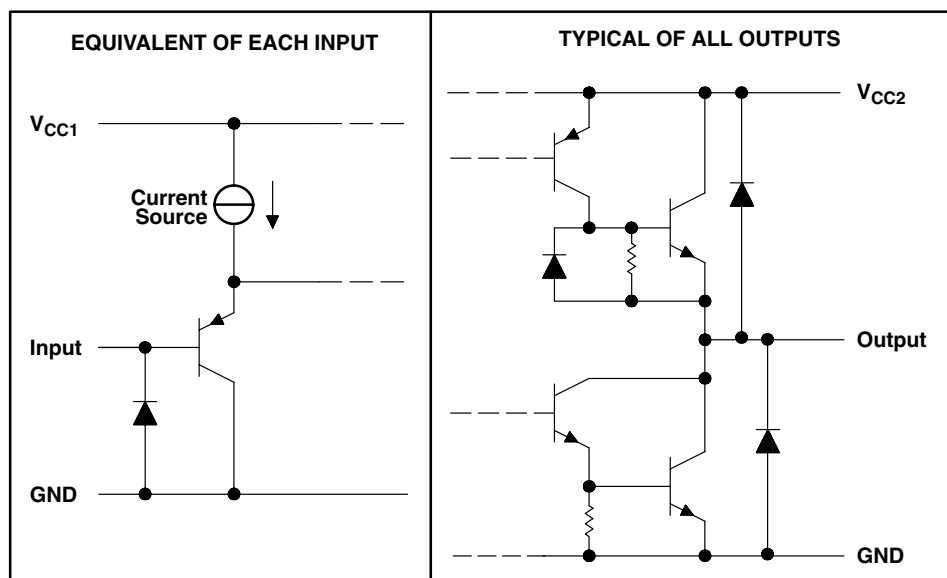
schematics of inputs and outputs (L293)



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schematics of inputs and outputs (L293D)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V_{CC1} (see Note 1)	36 V
Output supply voltage, V_{CC2}	36 V
Input voltage, V_I	7 V
Output voltage range, V_O	-3 V to $V_{CC2} + 3$ V
Peak output current, I_O (nonrepetitive, $t \leq 5$ ms): L293	± 2 A
Peak output current, I_O (nonrepetitive, $t \leq 100$ μ s): L293D	± 1.2 A
Continuous output current, I_O : L293	± 1 A
Continuous output current, I_O : L293D	± 600 mA
Package thermal impedance, θ_{JA} (see Notes 2 and 3): DWP package	TBD $^{\circ}$ C/W
N package	67 $^{\circ}$ C/W
NE package	TBD $^{\circ}$ C/W
Maximum junction temperature, T_J	150 $^{\circ}$ C
Storage temperature range, T_{stg}	-65 $^{\circ}$ C to 150 $^{\circ}$ C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. All voltage values are with respect to the network ground terminal.
 2. Maximum power dissipation is a function of $T_J(\text{max})$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(\text{max}) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150 $^{\circ}$ C can affect reliability.
 3. The package thermal impedance is calculated in accordance with JESD 51-7.

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recommended operating conditions

		MIN	MAX	UNIT
Supply voltage	V_{CC1}	4.5	7	V
	V_{CC2}	V_{CC1}	36	
V_{IH} High-level input voltage	$V_{CC1} \leq 7\text{ V}$	2.3	V_{CC1}	V
	$V_{CC1} \geq 7\text{ V}$	2.3	7	V
V_{IL} Low-level output voltage		-0.3†	1.5	V
T_A Operating free-air temperature		0	70	°C

† The algebraic convention, in which the least positive (most negative) designated minimum, is used in this data sheet for logic voltage levels.

electrical characteristics, $V_{CC1} = 5\text{ V}$, $V_{CC2} = 24\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
V_{OH} High-level output voltage		L293: $I_{OH} = -1\text{ A}$ L293D: $I_{OH} = -0.6\text{ A}$		$V_{CC2} - 1.8$	$V_{CC2} - 1.4$		V
V_{OL} Low-level output voltage		L293: $I_{OL} = 1\text{ A}$ L293D: $I_{OL} = 0.6\text{ A}$			1.2	1.8	V
V_{OKH} High-level output clamp voltage		L293D: $I_{OK} = -0.6\text{ A}$			$V_{CC2} + 1.3$		V
V_{OKL} Low-level output clamp voltage		L293D: $I_{OK} = 0.6\text{ A}$			1.3		V
I_{IH} High-level input current	A	$V_I = 7\text{ V}$			0.2	100	μA
	EN				0.2	10	
I_{IL} Low-level input current	A	$V_I = 0$			-3	-10	μA
	EN				-2	-100	
I_{CC1} Logic supply current	$I_O = 0$	All outputs at high level			13	22	mA
		All outputs at low level			35	60	
		All outputs at high impedance			8	24	
I_{CC2} Output supply current	$I_O = 0$	All outputs at high level			14	24	mA
		All outputs at low level			2	6	
		All outputs at high impedance			2	4	

switching characteristics, $V_{CC1} = 5\text{ V}$, $V_{CC2} = 24\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	L293NE, L293DNE			UNIT
		MIN	TYP	MAX	
t_{PLH} Propagation delay time, low-to-high-level output from A input	$C_L = 30\text{ pF}$, See Figure 1		800		ns
t_{PHL} Propagation delay time, high-to-low-level output from A input			400		ns
t_{TLH} Transition time, low-to-high-level output			300		ns
t_{THL} Transition time, high-to-low-level output			300		ns

switching characteristics, $V_{CC1} = 5\text{ V}$, $V_{CC2} = 24\text{ V}$, $T_A = 25^\circ\text{C}$

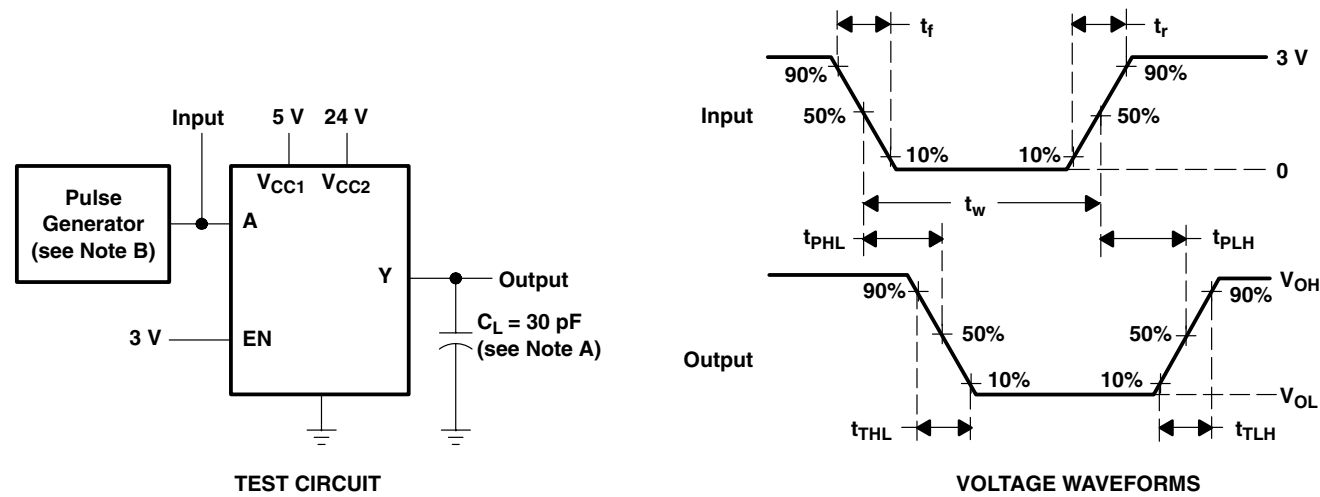
PARAMETER	TEST CONDITIONS	L293DWP, L293N L293DN			UNIT
		MIN	TYP	MAX	
t_{PLH} Propagation delay time, low-to-high-level output from A input	$C_L = 30\text{ pF}$, See Figure 1		750		ns
t_{PHL} Propagation delay time, high-to-low-level output from A input			200		ns
t_{TLH} Transition time, low-to-high-level output			100		ns
t_{THL} Transition time, high-to-low-level output			350		ns



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PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
B. The pulse generator has the following characteristics: $t_r \leq 10 \text{ ns}$, $t_f \leq 10 \text{ ns}$, $t_w = 10 \text{ }\mu\text{s}$, $\text{PRR} = 5 \text{ kHz}$, $Z_O = 50 \text{ }\Omega$.

Figure 1. Test Circuit and Voltage Waveforms

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APPLICATION INFORMATION

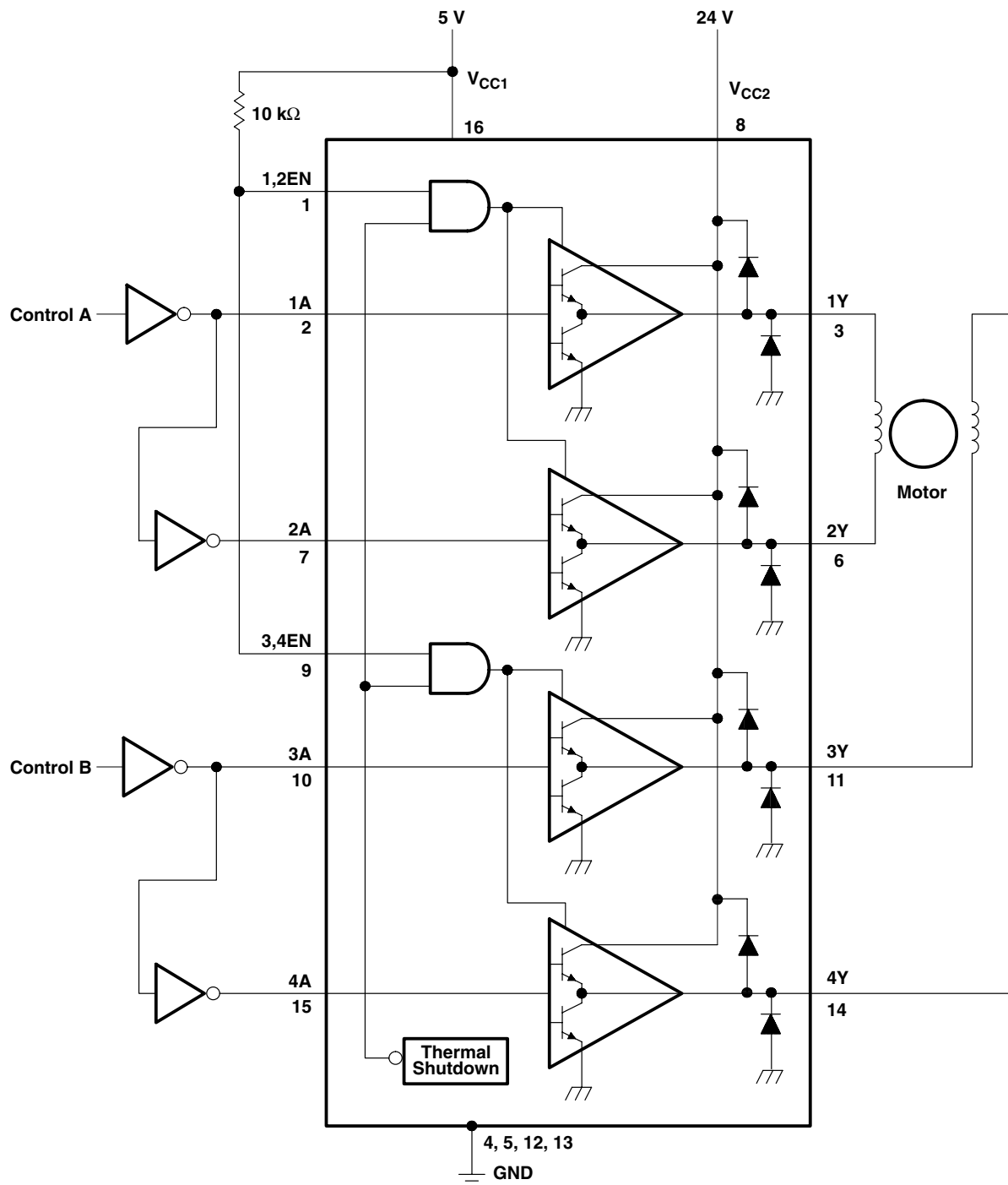


Figure 3. Two-Phase Motor Driver (L293D)

APPLICATION INFORMATION

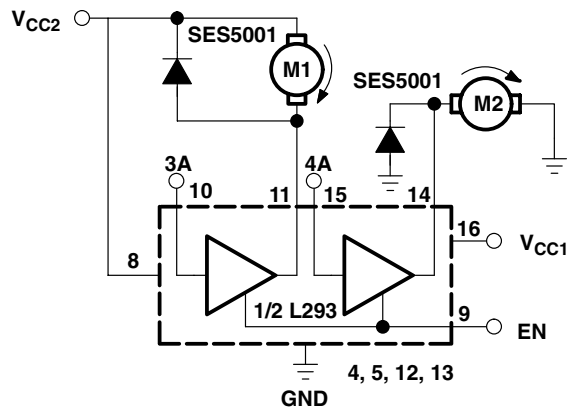


Figure 4. DC Motor Controls
(connections to ground and to
supply voltage)

EN	3A	M1	4A	M2
H	H	Fast motor stop	H	Run
H	L	Run	L	Fast motor stop
L	X	Free-running motor stop	X	Free-running motor stop

L = low, H = high, X = don't care

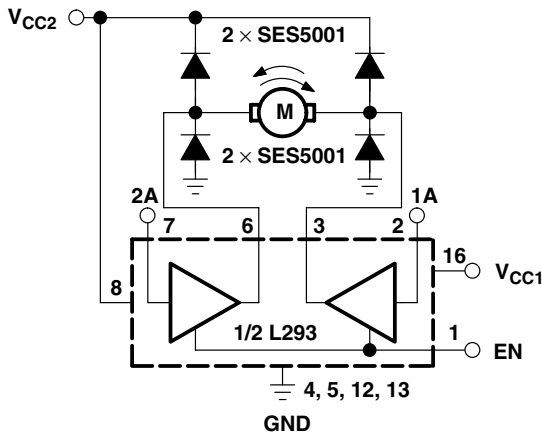


Figure 5. Bidirectional DC Motor Control

EN	1A	2A	FUNCTION
H	L	H	Turn right
H	H	L	Turn left
H	L	L	Fast motor stop
H	H	H	Fast motor stop
L	X	X	Fast motor stop

L = low, H = high, X = don't care

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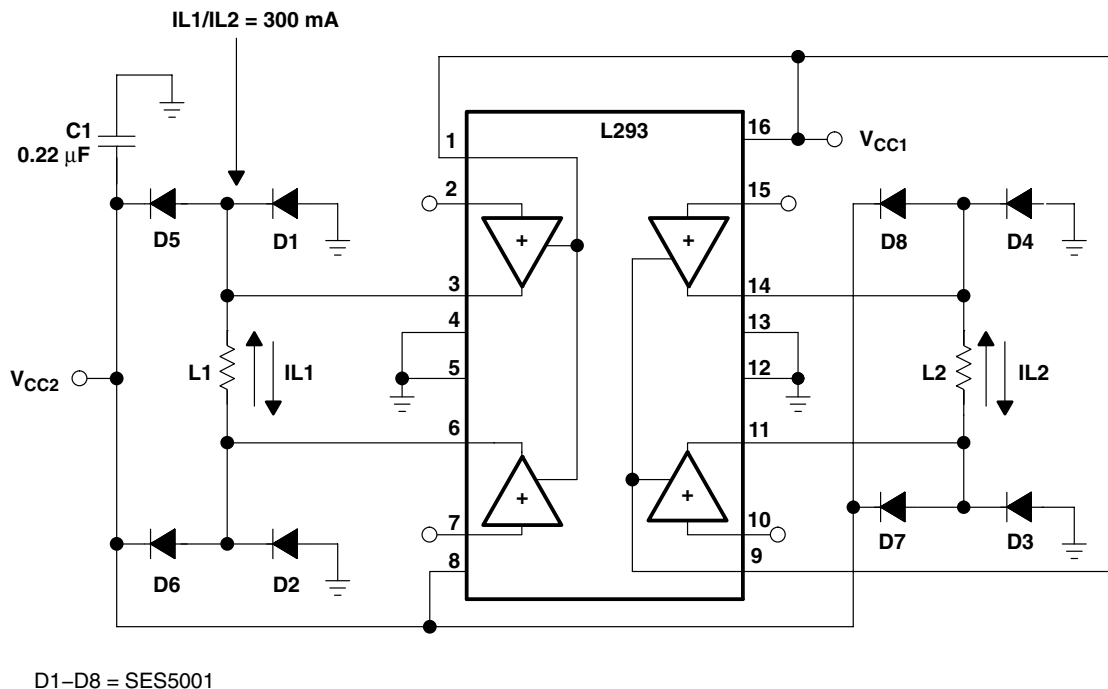


Figure 6. Bipolar Stepping-Motor Control

mounting instructions

The R_{thj-amp} of the L293 can be reduced by soldering the GND pins to a suitable copper area of the printed circuit board or to an external heat sink.

Figure 9 shows the maximum package power P_{TOT} and the θ_{JA} as a function of the side l of two equal square copper areas having a thickness of 35 μ m (see Figure 7). In addition, an external heat sink can be used (see Figure 8).

During soldering, the pin temperature must not exceed 260°C, and the soldering time must not exceed 12 seconds.

The external heatsink or printed circuit copper area must be connected to electrical ground.

APPLICATION INFORMATION

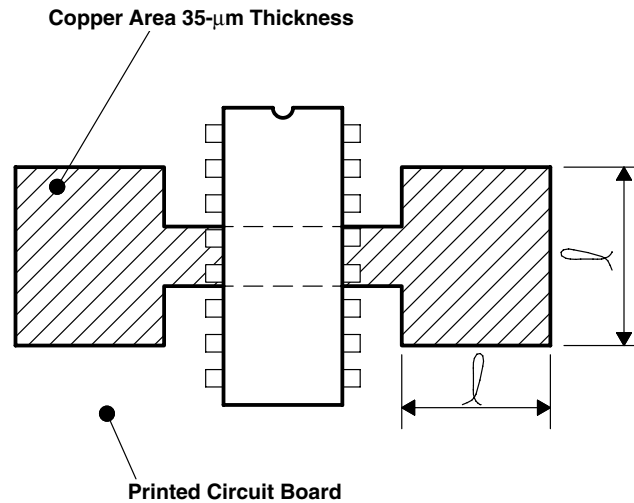


Figure 7. Example of Printed Circuit Board Copper Area (used as heat sink)

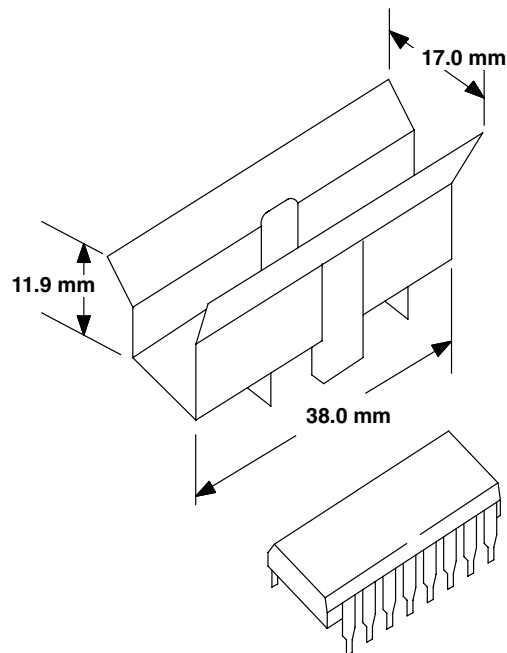


Figure 8. External Heat Sink Mounting Example
($\theta_{JA} = 25^{\circ}\text{C/W}$)

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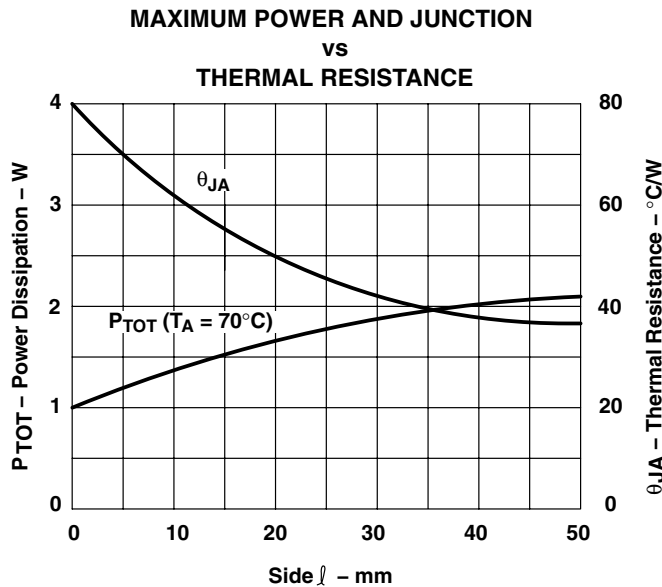


Figure 9

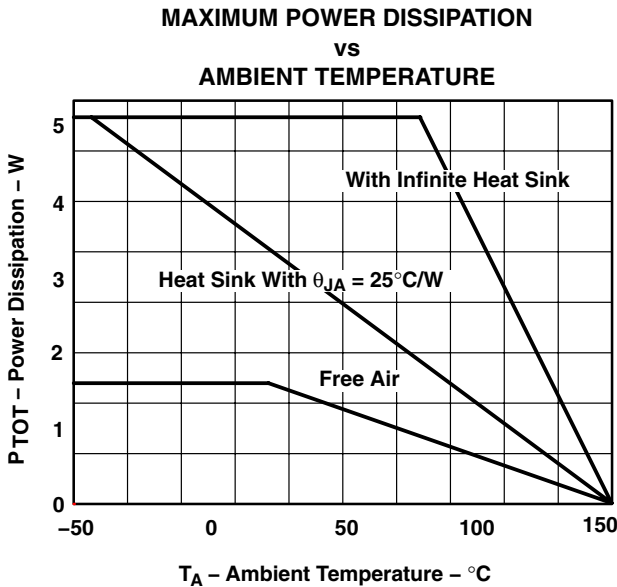


Figure 10

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
L293DNE	ACTIVE	PDIP	NE	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	L293DNE	Samples
L293DNEE4	ACTIVE	PDIP	NE	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	L293DNE	Samples
L293DWP	OBSOLETE	SOIC	DW	28		TBD	Call TI	Call TI	0 to 70	L293DWP	
L293DWPG4	OBSOLETE	SOIC	DW	28		TBD	Call TI	Call TI	0 to 70		
L293DWPTR	OBSOLETE	SO PowerPAD	DWP	28		TBD	Call TI	Call TI	0 to 70		
L293N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70	L293N	
L293NE	ACTIVE	PDIP	NE	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	L293NE	Samples
L293NEE4	ACTIVE	PDIP	NE	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	L293NE	Samples
L293NG4	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI	0 to 70		

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

⁽⁵⁾ Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

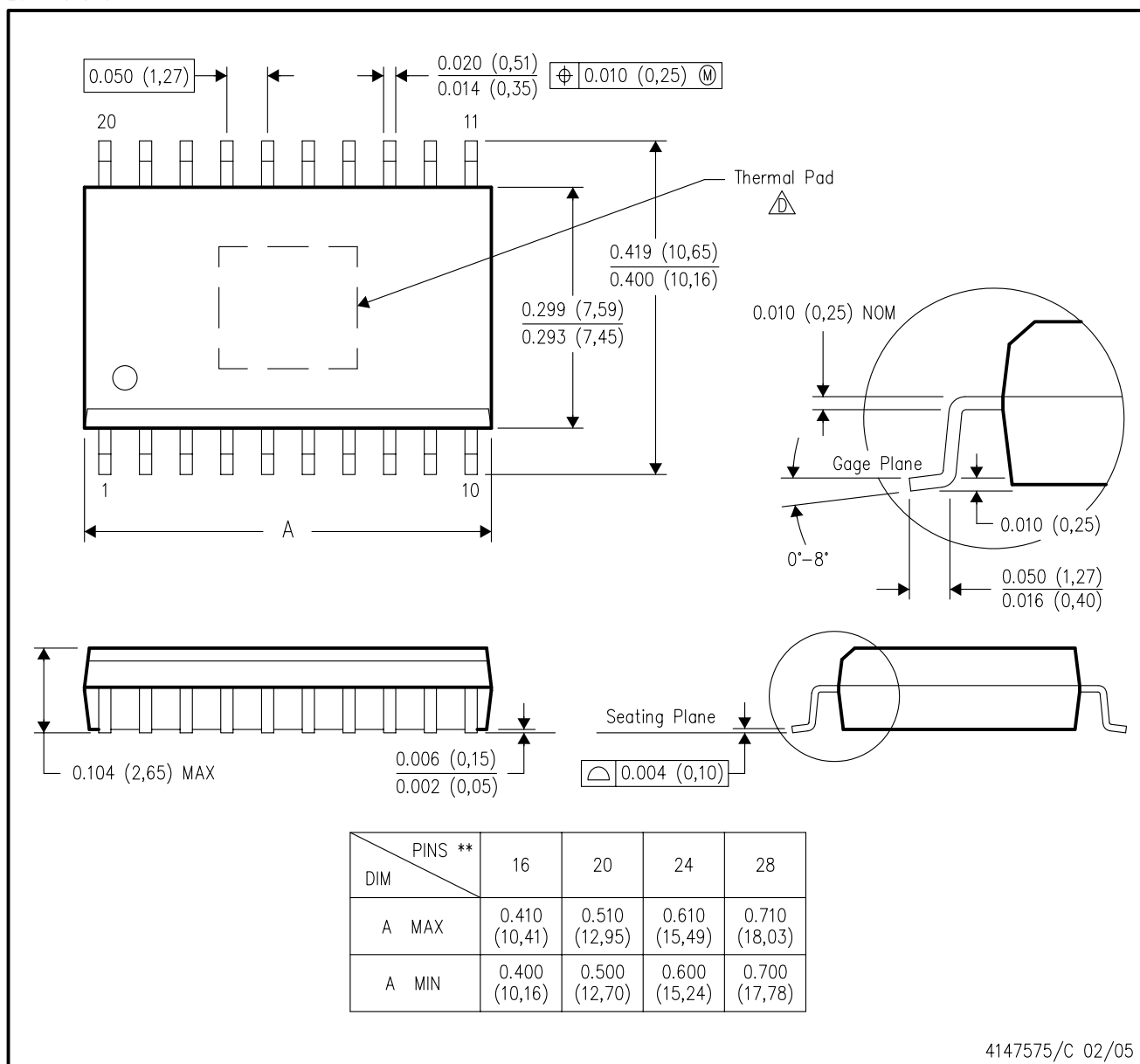
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DWP (R-PDSO-G**)

PowerPAD™ PLASTIC SMALL-OUTLINE PACKAGE

20 PINS SHOWN

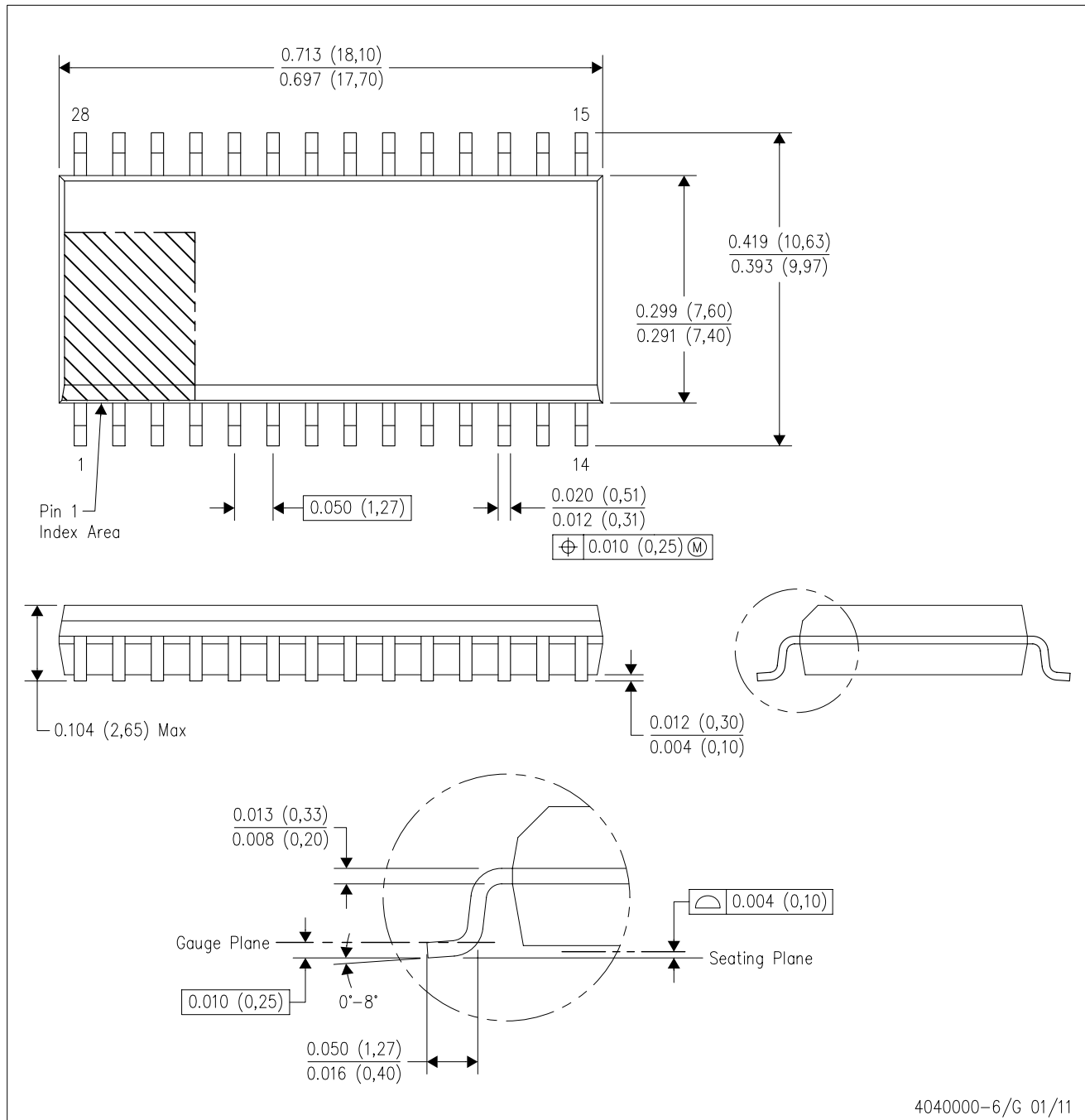


- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- △ This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com <<http://www.ti.com>>. See the product data sheet for details regarding the exposed thermal pad dimensions.

PowerPAD is a trademark of Texas Instruments.

DW (R-PDSO-G28)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013 variation AE.

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